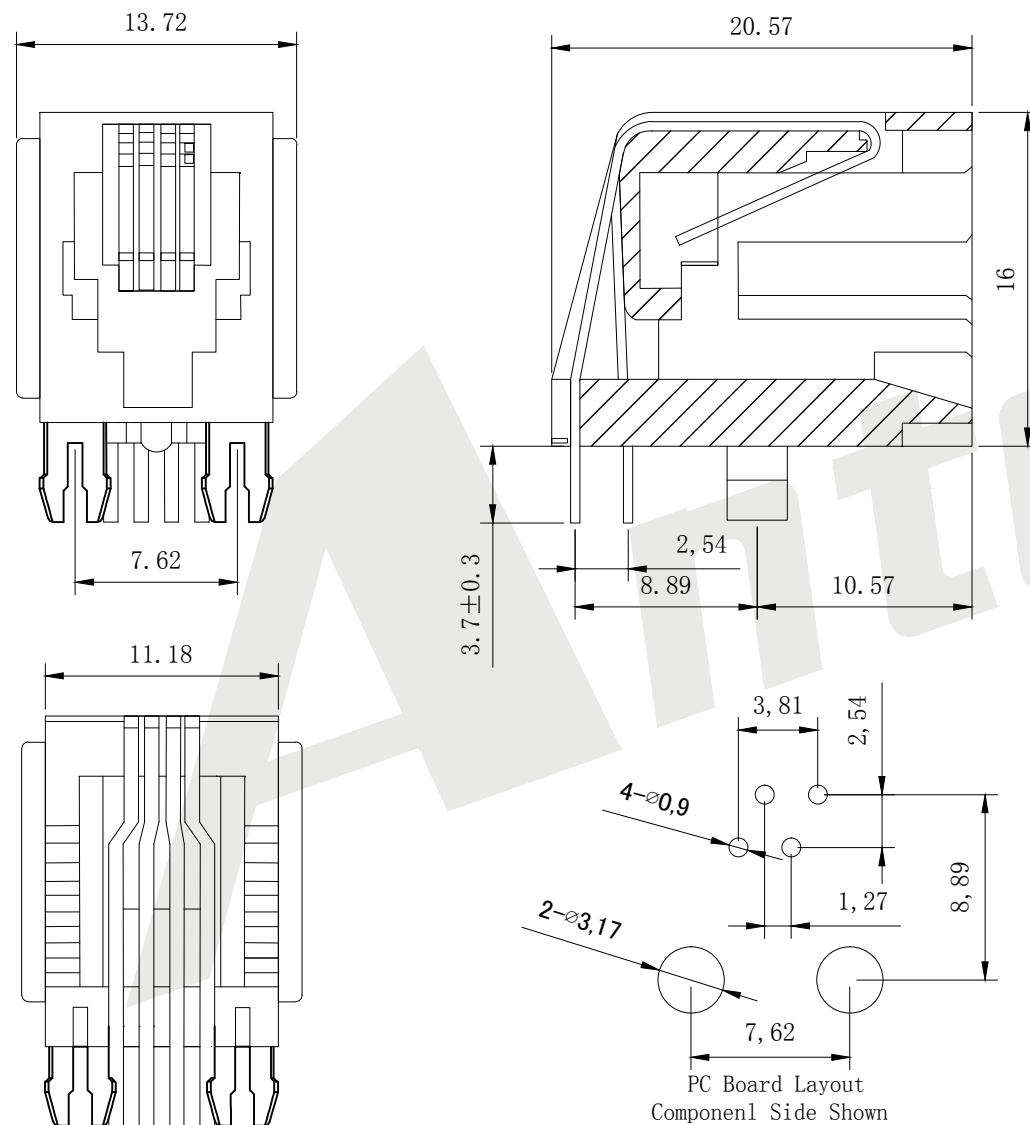


HSF

PC Board Layout
Component Side Shown

NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE $t=0.3\text{mm}$
3. PLATING: SELECTING GOLD PLATING $1\mu\sim 50\mu$ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATIN. OVER NICKEL IN SOLDER AREA

4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE

ELECTRICAL

1. VOLTAGE RATING: 125VAC RMS
2. CURRENT RATING: 1.5AMP
3. CONTACT RESISTANCE: 30MILLIOHMS MAX
4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTION PRB-SOLDER: 1 LB MIN

REVIROMENTAL

1. STORAGE: -40°C TO 85°C
2. OPERATION: 0°C TO 70°C

Order code:

ATRJ5721 - 4P - 4C - X - A - X - A

①	②	③	④	⑤	⑥	⑦
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- | | |
|------------------------------------|---------------------|
| ① SERIES NO: | ⑤ Shield |
| ② NUMBER OF POSITIONS (8P, 6P, 4P) | A: W/O Shield |
| ③ NUMBER OF CONTACTS (8C, 6C, 4C) | B: Half Shield |
| ④ Contact Plating | C: Shield W/Eml |
| G0: Gold flash | D: Shield W/O Eml |
| G1: 3U" Gold | ⑥ Ports |
| G2: 5U" Gold | A: 1X1P |
| G3: 10U" Gold | B: 1X2P |
| G4: 15U" Gold | C: 1X4P |
| G5: 30U" Gold | D: 1X5P |
| SN: Tin | E: 1X6P |
| | F: 1X8P |
| | ⑦ With Panel or not |
| | A: With panel |
| | B: Without panel |

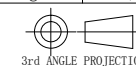
Unless Otherwise specified tolerance

X. ± 0.35	X. XX: ± 0.20
X. X: ± 0.25	X. XXX: ± 0.15

SCALE: As Shown	UNIT: mm
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DRAW Wu Feng Rong	DATE 22/03/2018
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CHECK BobYang	DATE 22/03/2018
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ANTENK ELECTRONICS CO., LTD

Http://www.antenk.com

E-mail:sales@antenk.com

TITLE: Modular Jack Side entry 4P4C
full Plastic with panel Flat pin

DRAWING NO: ATRJ5721-4P4C-X-A-X-A

PRODUCT NO: ATRJ5721-4P4C-X-A-X-A

REV

DESCRIPTION

DATE

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